

# Product Data Sheet

hm2.0 Female, type F,  
Part No. 246-31300-15

---

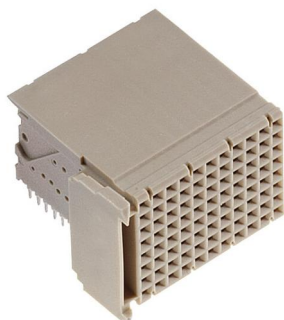


Illustration similar



Perpendicular



Press-fit

- number of positions 88
- tail length 2.9 mm
- for PCB thickness of at least 1.44 mm
- Available with and without shielding
- Tested in accordance with IEC 61076-4-101



» to product on [www.ept.de](http://www.ept.de)



» to product group hm 2.0

# Product Data Sheet

hm2.0 Female, type F,  
Part No. 246-31300-15



## Technical Specifications

### Basics

|                             |                      |
|-----------------------------|----------------------|
| Specification               | IEC 61076-4-101      |
| Performance Level           | 2                    |
| No. of Contacts             | 88                   |
| Termination Technology      | press-fit technology |
| Termination Length          | 2.9 mm               |
| Operating Temperature Range | -55°C to +125°C      |

### Material

|                               |                                       |
|-------------------------------|---------------------------------------|
| Insulator Material            | glass-fiber reinforced PBT, UL 94 V-0 |
| CTI value<br><i>IEC 60112</i> | 200                                   |
| Contact Material              | Bronze                                |

### Mechanical

|                          |                                              |
|--------------------------|----------------------------------------------|
| Pitch                    | 2.0 mm                                       |
| Mating Force per Pin     | Contact: max. 0.75 N, shielding: max. 1 N    |
| Separating Force per Pin | Contact: min. 0.15 N, shielding: min. 0.15 N |
| Durability               | > 250 mating cycles                          |

### Electrical

|                        |                                |
|------------------------|--------------------------------|
| Operational Current    | 1.5 A at +20°C, 1.0 A at +70°C |
| Test Voltage           | 750 V r.m.s.                   |
| Contact Resistance     | max. 20 mΩ                     |
| Clearance and Creepage | ≥ 0.6 mm                       |
| Insulation Resistance  | at least 10 <sup>4</sup> MΩ    |
| Data Transfer Rate     | 3.125 Gbit/s                   |

### Approval / Compliance

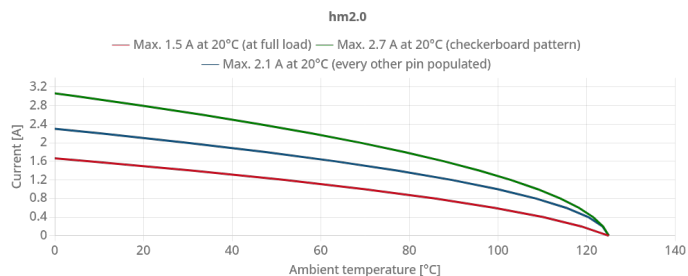
|             |                |
|-------------|----------------|
| UL file     | E130314        |
| Environment | RoHS compliant |

# Product Data Sheet

hm2.0 Female, type F,  
Part No. 246-31300-15



## Derating Diagram



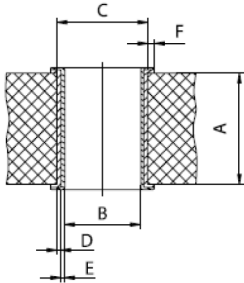
# Product Data Sheet

hm2.0 Female, type F,  
Part No. 246-31300-15



## Hole Specifications

Plated through-hole according to IEC 60352-5



| Material        | chem. Sn Schicht                    |
|-----------------|-------------------------------------|
| Nominal Hole    | Ø 0.6 mm                            |
| A PCB Thickness | min. 1.44 mm                        |
| B Plated Hole   | Ø 0.60 ±0.05 mm                     |
| C Drill Hole    | 0.70 ±0.02 mm                       |
| D Cu Plating    | min. 25 µm                          |
| E Surface       | max. 1.5 µm; chem. Sn Leiterplatten |
| F Annular Ring  | min. 0.1 mm                         |

| Material        | Ni, Au Leiterplatten                                |
|-----------------|-----------------------------------------------------|
| Nominal Hole    | Ø 0.6 mm                                            |
| A PCB Thickness | min. 1.44 mm                                        |
| B Plated Hole   | Ø 0.60 ±0.05 mm                                     |
| C Drill Hole    | 0.70 ±0.02 mm                                       |
| D Cu Plating    | min. 25 µm                                          |
| E Surface       | Ni, Au Schicht, 0.05 - 0.2 µm Au über 2.5 - 5 µm Ni |
| F Annular Ring  | min. 0.1 mm                                         |

| Material        | rein Cu Leiterplatten                          |
|-----------------|------------------------------------------------|
| Nominal Hole    | Ø 0.6 mm                                       |
| A PCB Thickness | min. 1.44 mm                                   |
| B Plated Hole   | Ø 0.60 ±0.05 mm                                |
| C Drill Hole    | 0.70 ±0.02 mm                                  |
| D Cu Plating    | min. 25 µm                                     |
| E Surface       | OSP*, z.B. GLICOAT-SMD (F2) mit 0.12 - 0.15 µm |
| F Annular Ring  | min. 0.1 mm                                    |

| Material        | HAL Sn Leiterplatten |
|-----------------|----------------------|
| Nominal Hole    | Ø 0.6 mm             |
| A PCB Thickness | min. 1.44 mm         |
| B Plated Hole   | Ø 0.60 ±0.05 mm      |
| C Drill Hole    | 0.70 ±0.02 mm        |
| D Cu Plating    | min. 25 µm           |
| E Surface       | HAL Sn, 5 - 15 µm    |
| F Annular Ring  | min. 0.1 mm          |

# Product Data Sheet

hm2.0 Female, type F,  
Part No. 246-31300-15

---



## Modifications

Available on request

- Other contact plating

## Accessories

- » hm2.0 lower shield plate, type F  
Part Number 246-31600-1

## Drawings

Component data in 2D and 3D format you can download here:

[» PDF](#)

[» 3D IGES](#)

[» 3D STEP](#)

[» 3D PDF](#)